

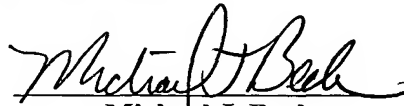
Please add the following claims:

31. A method of assembling a multi dynode device comprising:
placing a plurality of dynode plates onto an assembly frame in a stacked relationship; and
securing the stacked plurality of dynode plates together before removing the stack from the assembly frame,
wherein the assembly frame comprises inclined alignment pins, the inclined alignment pins defining a lateral offset amount, the plurality of dynode plates being laterally offset from one another in the stacked relationship by the lateral offset amount.
32. The method of assembling of Claim 31, wherein each dynode plate comprises a plurality of apertures, the apertures of each dynode plate being laterally offset from the apertures in adjacent dynode plates in the stacked relationship.
33. The method of assembling of Claim 31, wherein placing comprises guiding and orienting the dynode plates in the stacked relationship with respect to one another on the assembly frame using the inclined alignment pins.
34. The method of assembling of Claim 31, further comprising alternately placing a spacer ring of a plurality of spacer rings between adjacent dynode plates of the plurality, wherein securing the stacked plurality comprises securing together the alternately stacked plurality of dynode plates and spacer rings.
35. The method of assembling of Claim 31, further comprising applying a passive device material to a periphery of a surface of the dynode plates, the surface being the surface that faces an adjacent dynode plate when subsequently placed in the stacked relationship, the applied passive device material providing an integral spacer ring between adjacent dynode plates in the stacked relationship, the passive device material comprising one or both of a resistive material and a capacitive material, the

applied passive device material providing an integral bias network to the secured stacked plurality.

Respectfully submitted,

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Date: July 11, 2003

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